

AMENDMENT TRANSMITTAL LETTER (Small Entity)Applicant(s): **Donald Malcolm MacIntyre**

Docket No.

MAI1003Serial No.
09/045,507Filing Date
3/20/98Examiner
D. WilleGroup Art Unit
2814Invention: **CHIP SCALE PACKAGE****TO THE ASSISTANT COMMISSIONER FOR PATENTS:**

Transmitted herewith is an amendment in the above-identified application.

- ☒ Small Entity status of this application has been established under 37 CFR 1.27 by a verified statement previously submitted.
- ☐ A verified statement to establish Small Entity status under 37 FR 1.27 is enclosed.

The fee has been calculated and is transmitted as shown below.

CLAIMS AS AMENDED

	CLAIMS REMAINING AFTER AMENDMENT	HIGHEST # PREV. PAID FOR	NUMBER EXTRA CLAIMS PRESENT	RATE	ADDITIONAL FEE
TOTAL CLAIMS	6 -	20 =	0 x	\$9.00	\$0 00
INDEP. CLAIMS	2 -	3 =	0 x	\$39.00	\$0 00
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					\$0 00
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT					\$0 00

- ☒ No additional fee is required for amendment.
- ☐ Please charge Deposit Account No. _____ in the amount of _____
A duplicate copy of this sheet is enclosed.
- ☐ A check in the amount of _____ to cover the filing fee is enclosed.
- ☐ The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. _____
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- ☐ Any additional filing fees required under 37 C.F.R. 1.16.
- ☐ Any patent application processing fees under 37 CFR 1.17.

H. Donald Nelson
Signature

Dated: **2/22/99****H. Donald Nelson, Reg. No. 28,980**

I certify that this document and fee is being deposited
on **2/22/99** with the U.S. Postal Service as
first class mail under 37 C.F.R. 1.8 and is addressed to the
Assistant Commissioner for Patents, Washington, D.C.
20231

CC

H. Donald Nelson

Typed or Printed Name of Person Mailing Correspondence

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Donald Malcolm MacIntyre

Assignee: None

Title: CHIP SCALE PACKAGES

Serial No.: 09/045,507

Examiner: D. Wille

Attorney Docket No.: MAI1003



Filed: 3/20/98

Group Art Unit: 2814

San Jose, California
February 22, 1999

COMMISSIONER OF PATENTS AND TRADEMARKS
Washington, D.C. 20231

AMENDMENT

Sir:

In response to the Examiner's Office Action of 10/23/98, please amend the above-cited application as follows.

In the Specification

On page 1, line 16, please change "interconnect" to read - - interconnects - -.

On page 8, line 19, please change "300" to read - - 200 - -.

On page 8, line 20, please change "308" to read - - 208 - -.

In the Claims

Please amend the claims as follows. For the convenience of the Examiner, claims not amended are reproduced below in reduced font.

Please cancel Claims 1, 2, and 3 and substitute new Claim 15 therefor.

- - 15. (New) A chip scale structure comprising:

a semiconductor wafer with a pattern of bond pads on a surface of the semiconductor wafer, wherein the bond pads can be formed anywhere on the surface of the semiconductor wafer;

a glass sheet with holes in a pattern matching the pattern of bond pads on the surface of the semiconductor wafer;